3.14.01		OVER SHEET	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Honorable Commissi	101667432		d original documents or copy thereof.
1. Name of conveying party(ies)			of receiving party(ies)
Gabriele NELLES, Additional name(s) of convey Yes	, Akio YASUDA		of receiving party(les) nternational (Europe) GmbH Kemperplatz 1 D-10785 Berlin GERMANY
3. Nature of conveyance: X Assignment Security Agreement Merger Change of Name Other Execution Date: February 6, 200	<u>1</u>	Additional name(s) &	address(es) attached? <u>Yes x</u> No
the applicatio	nt is being filed together with	09/744,113) filed <u>18</u>	May 2000
5. Name and address of party to concerning document should b		6. Total number of a patents involved	pplications and
Name: WILLIAM S. FROMMER Internal Address: FROMMER LAWRENCE & HAUG LLP Street Address: 745 FIFTH AVENUE		7. Total fee (37 CFR 3.41) \$ 40.00 X Enclosed Authorized to be charged to deposit account 50-0320	
City: NEW YORK State: N.Y. Zip: 10151 8. Deposit account number: (Attach duplicate copy of this page if paying by deposed account)			
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copy of the original documen GORDON KESSLER		mation is true and core	March 14, 2001
Name of Person Signing	Signal		Date Total number of pages including cover sheet, attachments, and document: 2
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ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

METHOD FOR PROVIDING A SUBSTRATE STRUCTURE FOR ORIENTED NEURITE OUTGROWTH, SUBSTRATE STRUCTURE, AND DEVICE FOR MONITORING NEURONS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to

AND WHEREAS, SONY International (Europe) GmbH, a German corporation, with offices at Kemperplatz 1, D-10785 Berlin, GERMANY (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention. modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/EP00/04517
International Filing Date: 18 May 2000.

This assignment executed on the dates indicated below.

Gabriele NELLES			
Name of first or sole inventor	Execution date of U.S. Patent Application		
Y Stuttgart, Germany			
Residence of first or sole inventor	06/02/01		
Signature of first or sole inventor	Date of this assignment		
Akio YASUDA			
Name of second inventor	Execution date of U.S. Patent Application		
Y Stuttgart, Germany			
Residence of second inventor - Januards	86/02/01		
Signature of second inventor	Date of this assignment		
Name of third inventor	Execution date of U.S. Patent Application		
Residence of third inventor			
Signature of third inventor	Date of this assignment		

J:\SONY\03033\APPRECC.MSP (WSF:bkm)

RECORDED: 03/14/2001

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